

SCOPE OF CLAIMED INVENTION:

1. A semiconductor device characterized in comprising:
  - a first semiconductor chip mounted on a substrate;
  - a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;
  - a base member that is disposed between the second semiconductor chip and the substrate; and
  - a connection member disposed below the substrate, wherein the second semiconductor chip is supported by the base member.
  
2. A semiconductor device characterized in comprising:
  - a first semiconductor chip mounted on a substrate;
  - a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;
  - a filler layer that is provided between the second semiconductor chip and the substrate; and
  - a connection member disposed below the substrate, wherein the second semiconductor chip is supported by the filler layer.
  
3. A method for manufacturing a semiconductor device, the method characterized in comprising the steps of:
  - mounting a first semiconductor chip on a substrate;
  - mounting a base member outside the first semiconductor chip on the substrate; and
  - mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip, in a manner that the second semiconductor chip is supported by the base member.

4. A method for manufacturing a semiconductor device, the method characterized in comprising the steps of:
- mounting a first semiconductor chip on a substrate,
  - mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip; and
  - providing a filler layer in a manner to support the second semiconductor chip.